

## AMENDMENTS TO THE CLAIMS

Please amend the present application as follows:

### Claims

1. (Currently amended) An improved display A module, suitable for surface mounting comprising:
  - a substrate having a first side and a second side, the substrate defining one or more holes from the first side to the second side, the substrate additionally defining a recess located about the hole on the second side[[,]]; and
  - a plastic member for mounting to the first side of the substrate, the plastic member having one or more heat stakes received by the holes defined on comprising a thermoplastic heat stake having a shaped tip selected such that when reformed using heat, the thermoplastic material of the shaped tip forms a lump that is confined inside the recess of the substrate.
2. (Currently amended) A method of forming an improved display a surface mount module, the method suitable for surface mounting comprising:
  - forming providing a substrate having a first side and a second side[[,]];
  - forming one or more holes providing a hole in the substrate from the first side to the second side[[,]];
    - forming providing a recesses recess about the holes hole on the second side[[,]];
      - providing a plastic member having a thermoplastic heat stake;
      - mounting a the plastic member on the first side of the substrate, the mounting comprising insertion of the thermoplastic heat stake into the hole in the substrate; and plastic member having one or more heat stakes passing through the holes on the substrate, and
        - reforming the heat stakes into the recesses in the substrate;
        - heating a shaped tip of the thermoplastic heat stake whereby the thermoplastic material of the shaped tip is melted and confined inside the recess of the substrate.
3. (New) The module of claim 1, wherein the substrate is a printed circuit board (PCB) and the second side of the PCB is substantially planar for configuring the module as a surface mount module.

4. (New) The module of claim 1, wherein the shaped tip is a barbed tip.
5. (New) The module of claim 1, wherein the shaped tip is a tapered tip.
6. (New) The module of claim 1, wherein the shaped tip is a straight tip.
7. (New) The module of claim 1, wherein the recess is a V-shaped recess.
8. (New) The module of claim 1, wherein the recess is a U-shaped recess.
9. (New) The module of claim 1, wherein the recess comprises a first portion having straight sides and a second portion that is V-shaped.
10. (New) The module of claim 1, wherein the recess has a stepped cross section.
11. (New) The method of claim 2, further comprising:  
mounting the surface mount module upon a printed circuit board (PCB) using surface mounting techniques.
12. (New) The method of claim 2, wherein the shaped tip is selected to have a volume whereby when heated the thermoplastic material of the shaped tip is deformed and confined inside the recess of the substrate.
13. (New) A module, comprising:  
a substrate having a mounting hole extending from a first surface to a second surface, the mounting hole further defined by a recess located in the second surface; and  
a component that is mountable upon the first surface of the substrate, the component comprising a thermoplastic heat stake configured for insertion into the mounting hole in the substrate, the thermoplastic heat stake having a tip with a material volume that is selected for deforming under heat to produce a lump that is located, at least in part, inside the recess and is operative to securing the component to the substrate.

14. (New) The module of claim 13, wherein the lump is wholly confined inside the recess.
15. (New) The module of claim 14, wherein the second surface is substantially planar with the lump wholly confined inside the recess so as to provide surface mounting capability to the module.
16. (New) The module of claim 15, wherein the substrate and the component are parts of an electronic display.
17. (New) The module of claim 13, wherein the component is at least one of a) a light diffusing element or b) a reflector for reflecting light from a light source mounted on the substrate.
18. (New) The module of claim 17, wherein the light diffusing element is a plastic light diffusing element.
19. (New) The module of claim 13, wherein the substrate is a printed circuit board (PCB).
20. (New) The module of claim 19, wherein the PCB has a thickness approximately 1.6 mm.